



NSAI
Standards

Irish Standard
I.S. EN 62258-1:2010

Semiconductor die products -- Part 1: Procurement and use (IEC 62258 -1:2009 (EQV))

I.S. EN 62258-1:2010

Incorporating amendments/corrigenda issued since publication:

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SWiFT xxx: A rapidly developed recommendatory document based on the consensus of the participants of an NSAI workshop.

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English version

Semiconductor die products -
Part 1: Procurement and use
(IEC 62258-1:2009)

Produits de puces de semiconducteurs -
Partie 1: Approvisionnement et utilisation
(CEI 62258-1:2009)

Halbleiter-Chip-Erzeugnisse -
Teil 1: Beschaffung und Anwendung
(IEC 62258-1:2009)

This European Standard was approved by CENELEC on 2010-10-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47/1974/CDV, future edition 2 of IEC 62258-1, prepared by IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 62258-1 on 2010-10-01.

This European Standard supersedes EN 62258-1:2005.

The main changes that have been introduced in this issue have been to ensure consistency across all parts of the standard. The ordering of the subclauses, particularly in Clause 6, has been changed to be more logical and the text of some of the requirements has been amended to add requirements on further information as covered by CLC/TR 62258-4, CLC/TR 62258-7 and CLC/TR 62258-8. New requirements include information on permutability of terminals and functional elements (6.6.4) and moisture sensitivity for partially encapsulated devices (8.8).

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2011-07-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2013-10-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 62258-1:2009 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068 series	NOTE	Harmonized in EN 60068 series (not modified).
IEC 60749-26	NOTE	Harmonized as EN 60749-26.
IEC 60749-27	NOTE	Harmonized as EN 60749-27.
IEC 61340-5-1	NOTE	Harmonized as EN 61340-5-1.
IEC 61340-5-2	NOTE	Harmonized as EN 61340-5-2.
IEC 61340-5-2	NOTE	Harmonized as EN 61340-5-2.
ISO 9000	NOTE	Harmonized as EN ISO 9000.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	Series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 60191	Series	Mechanical standardization of semiconductor devices	EN 60191	Series
IEC 60191-4 + A1 + A2	1999 2001 2002	Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of package outlines for semiconductor device packages	EN 60191-4 + A1 + A2	1999 2002 2002
IEC 61360-1	-	Standard data elements types with associated classification scheme for electric items - Part 1: Definitions - Principles and methods	EN 61360-1	-
IEC 62258-2	-	Semiconductor die products - Part 2: Exchange data formats	EN 62258-2	-
IEC/TR 62258-3	-	Semiconductor die products - Part 3: Recommendations for good practice in handling, packing and storage	CLC/TR 62258-3	-
IEC/TR 62258-4	-	Semiconductor die products - Part 4: Questionnaire for die users and suppliers	CLC/TR 62258-4	-
IEC 62258-5	-	Semiconductor die products - Part 5: Requirements for information concerning electrical simulation	EN 62258-5	-
IEC 62258-6	-	Semiconductor die products - Part 6: Requirements for information concerning thermal simulation	EN 62258-6	-
IEC/TR 62258-7	-	Semiconductor die products - Part 7: XML schema for data exchange	CLC/TR 62258-7	-
IEC/TR 62258-8	-	Semiconductor die products - Part 8: EXPRESS model schema for data exchange	CLC/TR 62258-8	-
ISO 14644-1	1999	Cleanrooms and associated controlled environments - Part 1: Classification of air cleanliness	EN ISO 14644-1	1999

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CONTENTS

FOREWORD.....	5
INTRODUCTION.....	7
1 Scope.....	8
2 Normative references.....	8
3 Terms and definitions	9
3.1 Basic definitions	9
3.2 General terminology	10
3.3 Semiconductor manufacturing and interconnection terminology.....	12
4 General requirements	13
5 Data exchange	13
6 Requirements for all devices.....	14
6.1 Data package	14
6.1.1 General	14
6.1.2 Information source	14
6.1.3 Data version	14
6.1.4 Data exchange formats	14
6.2 Identity and source	14
6.2.1 General	14
6.2.2 Type number	14
6.2.3 Manufacturer	14
6.2.4 Supplier	14
6.2.5 Signature	14
6.3 Function	14
6.4 Physical characteristics	15
6.4.1 Semiconductor material	15
6.4.2 Technology.....	15
6.5 Ratings and limiting conditions.....	15
6.5.1 Power dissipation.....	15
6.5.2 Operating temperature	15
6.6 Connectivity.....	15
6.6.1 General	15
6.6.2 Terminal count.....	15
6.6.3 Terminal information	15
6.6.4 Permutability.....	16
6.7 Documentation	16
6.8 Form of supply.....	16
6.8.1 Physical form	16
6.8.2 Packing	16
6.9 Simulation and modelling	16
6.9.1 General	16
6.9.2 Electrical modelling and simulation.....	16
6.9.3 Thermal data and modelling	16
7 Requirements for bare die and wafers with or without connection structures	17
7.1 General	17
7.2 Identity	17
7.2.1 General	17

7.2.2	Die name	17
7.2.3	Die version	17
7.3	Materials	17
7.3.1	Substrate material	17
7.3.2	Substrate connection	17
7.3.3	Backside detail	17
7.3.4	Passivation material	17
7.3.5	Metallisation	17
7.3.6	Terminal material	17
7.3.7	Terminal structure	18
7.3.8	Vias	18
7.4	Geometry	18
7.4.1	General	18
7.4.2	Units of measurement	18
7.4.3	Geometric view	18
7.4.4	Die size	18
7.4.5	Die thickness	18
7.4.6	Dimension tolerances	18
7.4.7	Geometric origin	18
7.4.8	Terminal shape and size	18
7.4.9	Die fiducials	19
7.4.10	Die picture	19
7.5	Wafer data	19
7.5.1	General	19
7.5.2	Wafer size	19
7.5.3	Wafer index	19
7.5.4	Wafer die count and step size	19
7.5.5	Wafer reticules	19
8	Minimally-packaged devices	19
8.1	General	19
8.2	Number of terminals	19
8.3	Terminal position	19
8.4	Terminal shape and size	20
8.5	Device size	20
8.6	Seated height	20
8.7	Encapsulation material	20
8.8	Moisture sensitivity	20
8.9	Package style code	20
8.10	Outline drawing	20
9	Quality, test and reliability	21
9.1	General	21
9.2	Outgoing quality level	21
9.2.1	Value	21
9.2.2	Description	21
9.3	Electrical parameters specified	21
9.4	Compliance to standards	21
9.5	Additional device screening	21
9.6	Product status	21
9.7	Testability features	21

9.8	Additional test requirements.....	21
9.9	Reliability.....	22
9.9.1	Reliability estimate.....	22
9.9.2	Reliability calculation	22
10	Handling and packing	22
10.1	General requirements for all devices.....	22
10.1.1	General	22
10.1.2	Customer part number	22
10.1.3	Type number	23
10.1.4	Supplier	23
10.1.5	Manufacturer	23
10.1.6	Traceability.....	23
10.1.7	Quantity.....	23
10.1.8	ESD sensitivity.....	23
10.1.9	Requirements for environmental protection	23
10.2	Specific requirement for bare die or wafers – mask version	23
10.3	Specific requirement for wafers – wafer map.....	23
10.4	Special item requirements	23
10.4.1	General	23
10.4.2	Special protection requirements	24
10.4.3	Unencapsulated die warning label	24
10.4.4	Toxic material warning	24
10.4.5	Fragile components warning	24
10.4.6	ESD sensitivity warning.....	24
11	Storage	24
11.1	General	24
11.2	Storage duration and conditions.....	24
11.3	Long-term storage	24
11.4	Storage limitations	24
12	Assembly.....	25
12.1	General	25
12.2	Attach methods and materials.....	25
12.3	Bonding method and materials.....	25
12.4	Attachment limitations.....	25
12.4.1	General	25
12.4.2	Temperature/time profile.....	25
12.5	Process limitations	25
	Annex A (informative) Terminology.....	26
	Annex B (informative) Acronyms.....	36
	Bibliography	43

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

Part 1: Procurement and use

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 62258-1 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2005, and constitutes a technical revision.

The main changes that have been introduced in this issue have been to ensure consistency across all parts of the standard. The ordering of the subclauses, particularly in Clause 6, has been changed to be more logical and the text of some of the requirements has been amended to add requirements on further information as covered by IEC/TR 62258-4, IEC/TR 62258-7 and IEC/TR 62258-8. New requirements include information on permutability of terminals and functional elements (6.6.4) and moisture sensitivity for partially encapsulated devices (8.8).

The text of this standard is based on the following documents:

CDV	Report on voting
47/1974/CDV	47/2004/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 62258 series, under the general title *Semiconductor die products*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This standard is based on the work carried out in the ESPRIT 4th Framework project GOOD-DIE which resulted in the publication of the ES59008 series of European specifications. Organisations that helped prepare this document included the European IST ENCASIT project, JEITA, JEDEC and ZVEI.

The structure of this International Standard as currently conceived is as follows:

- Part 1: Procurement and use
- Part 2: Exchange data formats
- Part 3: Recommendations for good practice in handling, packing and storage (technical report)
- Part 4: Questionnaire for die users and suppliers (technical report)
- Part 5: Requirements for information concerning electrical simulation
- Part 6: Requirements for information concerning thermal simulation
- Part 7: XML schema for data exchange (technical report)
- Part 8: EXPRESS model schema for data exchange (technical report)

Further parts may be added as required.

SEMICONDUCTOR DIE PRODUCTS –

Part 1: Procurement and use

1 Scope

This part of IEC 62258 has been developed to facilitate the production, supply and use of semiconductor die products, including

- wafers,
- singulated bare die,
- die and wafers with attached connection structures,
- minimally or partially encapsulated die and wafers.

The standard defines the minimum requirements for the data that are needed to describe such die products and is intended as an aid to the design of and procurement for assemblies incorporating die products. It covers the requirements for data, including

- product identity
- product data
- die mechanical information
- test, quality, assembly and reliability information
- handling, shipping and storage information

It covers the specific requirements for the data that are needed to describe the geometrical properties of die, their physical properties and the means of connection necessary for their use in the development and manufacture of products. It also contains, in the annexes, a vocabulary and list of common acronyms.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050 (all parts), *International Electrotechnical Vocabulary*

IEC 60191 (all parts), *Mechanical standardization of semiconductor devices*

IEC 60191-4:1999, *Mechanical standardization of semiconductor devices – Part 4: Coding system and classification into forms of package outlines for semiconductor device packages*
Amendment 1 (2001)
Amendment 2 (2002)

IEC 61360-1, *Standard data element types with associated classification scheme for electric components – Part 1: Definitions – Principles and methods*

IEC 62258-2, *Semiconductor die products – Part 2: Exchange data formats*

IEC/TR 62258-3, *Semiconductor die products – Part 3: Recommendations for good practice in handling, packing and storage*

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